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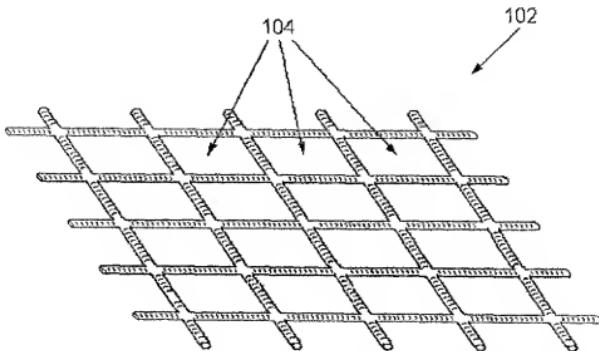
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(54) Title: THERMAL INTERFACE MATERIAL ON A MESH CARRIER



(57) Abstract: A thermal interface comprising a grid frame having a thermally conductive interface material coated thereon. The thermal interface is disposed between a heat source and a heat dissipation device wherein the thermally conductive material preferably melts at a temperature at or below the temperature of the heat source.

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## THERMAL INTERFACE MATERIAL ON A MESH CARRIER

BACKGROUND OF THE INVENTION

Field of the Invention: The present invention relates to apparatus and methods for removal of heat from electronic devices. In particular, the present invention relates to a thermal interface comprising a grid frame coated with a thermal interface material, wherein the coated grid frame is disposed between a heat generating source, such as a microelectronic die, and a heat dissipation device, such as a heat spreader or heat sink.

State of the Art: Higher performance, lower cost, increased miniaturization of integrated circuit components, and greater packaging density of integrated circuits are ongoing goals of the microelectronic and computer industry. As these goals are achieved, microelectronic dice become smaller. Accordingly, the density of power consumption of the integrated circuit components in the microelectronic die has increased, which, in turn, increases the average junction temperature of the microelectronic die. If the temperature of the microelectronic die becomes too high, the integrated circuits of the microelectronic die may be damaged or destroyed.

Various apparatus and techniques have been used and are presently being used for removing heat from microelectronic dice. One such heat dissipation technique involves the attachment of a heat dissipation device to a microelectronic die. FIG. 4 illustrates an assembly 200 comprising a microelectronic die 202 (illustrated as a flip chip) physically and electrically attached to a carrier substrate 204 by a plurality of solder balls 206. A back surface 216 of a heat dissipation device 208 may be attached to a back surface 212 of the microelectronic die 202 by a thermally conductive adhesive or solder 214. The heat dissipation device 208 may be a heat pipe, as known in the art, or a heat slug

constructed from a thermally conductive material, such as copper, copper alloys, aluminum, aluminum alloys, and the like.

However, the use of a rigid thermally conductive adhesive or solder 214 can cause stresses in the microelectronic die 202 due to a mismatch between coefficients of thermal expansion ("CTE") of the heat dissipation device 208 and the microelectronic die 202 as the microelectronic die 202 heats to a normal operating temperature when on and room temperature when off. Stresses due to CTE mismatch increase the probability that cracks will initiate and propagate in the microelectronic die 202, which may cause the failure of the microelectronic die 202. Furthermore, in order to get the solder materials to adhere to the microelectronic die back surface 212 and the heat dissipation device back surface 216, a gold coating may to be applied to both surfaces, which is prohibitively expensive.

In another known embodiment as shown in FIG. 5, a pin grid array-type ("PGA") microelectronic die 222 is placed in a socket 224 mounted on the carrier substrate 204, wherein pins 226 extending from the PGA microelectronic die 222 make electrical contact with conductive vias 228 in the socket 224. The socket 224 is, in turn, in electrical contact (not shown) with the carrier substrate 204. The heat dissipation device 208 (shown as a finned heat sink having a plurality of fins 232) is kept in contact with the microelectronic die 222 with a spring clip 234 which spans the heat dissipation device 208 and connects to the socket 224. A conductive grease 236 is placed between the microelectronic die 202 and the heat dissipation device 208. This configuration virtually eliminates problems with CTE mismatch.

It is also known that the conductive grease 236 of FIG. 5 may be replaced with a phase-change material or matrix. Such materials are in a substantially solid phase (paste-like consistency) when cool (i.e., room temperature). When heated (brought to

operating temperatures), the phase-change material changes to a substantially liquid phase (grease-like consistency) which allows the phase-change material to conform to surface irregularities of mating surfaces (when in a solid phase the phase change material is not able to conform to all microwarpages). Therefore the liquid phase has better 5 contact properties which results in a higher heat dissipation compared to the solid phase. One such material is Thermflow™ T443, consisting of a phase-change material within a fiberglass carrier (mat/pad) available from Chomerics, Woburn, MA, USA.

However, as the size or "footprint" of microelectronic dice decreases, the contact area between the microelectronic die and the heat dissipation device decreases, which 10 reduces the area available for conductive heat transfer. Thus, with a decrease of the size in the microelectronic die, heat dissipation from the heat dissipation device becomes less efficient. Furthermore, as the microelectronic die power is increased, the heat source upper temperature specifications decreases, or the external ambient temperature specification increases. Thus, every area of thermal performance must be examined for 15 any possible enhancement. One such area is the interface between the microelectronic die and the heat dissipation device. As microelectronic dice become smaller, the heat transfer properties of the interface becomes a greater factor. Thus, currently available thermally conductive adhesives, greases, and phase-change materials generally are quickly becoming bottlenecks to heat dissipation.

20 Therefore, it would be advantageous to develop techniques and apparatus to improve the efficiency of heat transfer at an interface between a heat source and a heat dissipation device.

BRIEF DESCRIPTION OF THE DRAWINGS

While the specification concludes with claims particularly pointing out and distinctly claiming that which is regarded as the present invention, the advantages of this invention can be more readily ascertained from the following description of the 5 invention when read in conjunction with the accompanying drawings in which:

FIG. 1 is an oblique view of an embodiment of a grid frame, according to the present invention;

FIG. 2 is a side cross-sectional view of an embodiment of a grid frame coated with a solder material, according to the present invention;

10 FIG. 3 is a side cross-sectional view of an embodiment of a microelectronic assembly having a coated grid frame thermal interface, according to the present invention;

FIG. 4 is a side cross-sectional view of a heat dissipation device attached to microelectronic die, as known in the art; and

15 FIG. 5 is a side cross-sectional view of a heat dissipation device clipped to PGA microelectronic die, as known in the art.

DETAILED DESCRIPTION OF THE ILLUSTRATED EMBODIMENT

Although the figures illustrate various views of the present invention, these figures 20 are not meant to portray microelectronic assemblies in precise detail. Rather, these figures illustrate microelectronic assemblies in a manner to more clearly convey the concepts of the present invention. Additionally, elements common between the figures retain the same numeric designation.

Although the present invention is described in terms of microelectronic dice and microelectronic-type heat dissipation devices, it is not so limited. The present invention may be used as an interface between any applicable heat source and heat dissipation mechanism.

5 FIG. 1 illustrates a grid frame 102 of the present invention. The grid frame 102 may be made of a thermally conductive material including, but not limited to, aluminum, copper, nickel, stainless steel, and the like. Preferably the grid frame 102 is fabricated by providing a metal foil and placing slits/perforations therethrough. The metal foil is expanded/stretched and rolled flat. However, it is understood that numerous fabrication 10 techniques may be employed to fabricate the grid frame 102, as will be apparent to one skilled in the art. Furthermore, although the openings 104 in the grid frame 102 are shown to be square, they may be any shape including, but not limited to, triangular, rectangular, circular, elliptical, and the like, depending on the fabrication technique.

The grid frame 102 is then coated with a thermally conductive interface material 106. FIG. 2 illustrates a cross-sectional view of the grid frame 102 coated with the thermally conductive interface material 106 to form a coated grid frame 108. The thermally conductive interface material 106 preferably has a melting temperature at or lower temperature than the temperature of the heat source to which the coated grid frame 108 will subsequently abutted. It is, of course, understood that the actual profile and 20 depth of the coating will depend on the physical properties of the thermally conductive interface material 106 selected and the size of the openings 104 (see FIG. 1) of the grid frame 102.

FIG. 3 illustrates a microelectronic component assembly 110 according to one embodiment of the present invention. The microelectronic component assembly 110

includes a microelectronic device package 118 comprising a microelectronic die 112 attached to and in electrical contact with a first surface 116 of an interposer substrate 114. The attachment and electrical contact is achieved through a plurality of small solder balls 122 extending between contacts 124 on the microelectronic die 112 and contacts 126 on the interposer substrate first surface 116. The interposer substrate first surface contacts 126 are in discrete electrical contact with contacts 134 on a second surface 136 of the interposer substrate 114 through a plurality of conductive traces (not shown) extending through the interposer substrate 114.

10 The electrical contact of the microelectronic device package 118 with a carrier substrate (such as a motherboard) 142 is achieved with a plurality of solder balls 144, which are formed (reflow) on the interposer substrate second surface contacts 134. The solder balls 144 extend between the interposer substrate second surface contacts 134 and contacts 146 on a first surface 148 of the carrier substrate 142 to form an electrical contact therebetween.

15 The support structure 152 includes a frame 154, a backing plate 156, a heat dissipation plate 158, and a plurality of retention devices (shown as bolts 162 and nuts 164). The backing plate 156 is placed adjacent a second surface 166 of the carrier substrate 142. The frame 154 is placed adjacent to the carrier substrate first surface 148 and at least partially surrounds the microelectronic device package 118.

20 The coated grid frame 108 is disposed between the heat dissipation plate 158 and the microelectronic die 112. The heat dissipation plate 158 extends over the frame 154. The bolts 162 extend through the backing plate 156, the frame 154, and the heat dissipation plate 158, and are retained by nuts 164 threaded thereon. The heat dissipation plate 158 is made of a highly thermally conductive material including, but

not limited to, aluminum, aluminum alloys, copper, and copper alloys. The heat dissipation plate 158 dissipates the heat generated by the microelectronic die 112. It is, of course, understood that other retention mechanisms, such as clips and the like, could be used as the support structure 152.

5 In one embodiment of the present invention (referring back to FIG. 2), the grid frame 102 comprises a copper mesh having a strand width 172 of about 5 mils and an overall thickness 174 of about 1.5 mils. The individual grids (see FIGs. 1 and 2) have a pitch 176 of about 50 mils. It is noted that the mesh should be as thin as viably possible.

10 The thermally conductive interface material 106 is selected such at it melts at or below the normal operation temperature of the microelectronic die 112. In the present embodiment, the thermally conductive interface material is a solder (and will hereinafter be designed with the "106" element numbering) having a melting temperature of about 60°C. Possible solder materials include, but are not limited to, a lead solder having about 49% Bi, about 21% In, about 18% Pb, and about 12% Sn; and a lead-free solder  
15 having about 51% In, about 32.5% Bi, and about 16.5% Sn. The exemplary lead and lead-free solders both have a melting temperature of about 60°C. The grid frame 102 can be coated with the solder 106 by melting it and dipping the grid frame 102 in the melted solder 106, such that the solder 106 completely coats the grid frame 102. It is, of course, understood that the grid frame 102 may be coated with the solder 106 using a  
20 number of techniques, as will be apparent to one skilled in the art. The coated grid frame 108 can then be placed between the heat dissipation plate 158 and the microelectronic die 112, with positive pressure therebetween induced by the support structure 152.

When the microelectronic die 112 is powered up, it generates heat, raising its temperature. Thus, when the temperature of the microelectronic die 112 is increased above the melting temperature of the solder 106, the solder 106 melts and conforms to the microelectronic die 112 and the heat dissipation plate 158 in an intimate, low thermal 5 resistance contact therebetween. This enhances heat transfer from the microelectronic die 112 to the heat dissipation plate 158. The grid frame 102 mechanically keeps the solder 106 from running out of the interface between the microelectronic die 112 and the heat dissipation plate 158. It is believed the cohesion of the solder retains the melted solder 106 on the grid frame 102, rather than the solder 106 sticking to the grid frame. 10 The melted solder 106 will tend to flow completely out of the interface between the microelectronic die 112 and the heat dissipation plate 158 without the grid frame 102, as the melted solder 106 generally does not wet either the microelectronic die 112 or the heat dissipation plate 158.

When the microelectronic die 112 cools below the melting point of the solder 106, 15 the solder 106 solidifies. The melting point of the solder 106 is preferably at or above room temperature (i.e., about 72°C). As the solder 106 cools, a weak adhesion develops between the solder 106 and either or both of the microelectronic die 112 and the heat dissipation plate 158. Thus, the CTE mismatch will result in the de-coupling the microelectronic die 112 from the heat dissipation plate 158, thereby eliminating stresses 20 caused by CTE mismatch. In other words, the solidified solder 106 breaks free from the microelectronic die and/or the heat dissipation plate 158. Furthermore, no special coating for the microelectronic die 112 and/or the heat dissipation plate 158 is needed.

In a comparison between the above described grid frame (i.e., 1.5 mil copper with a 50 mil pitch) with the lead solder coating (about 49% Bi, about 21% In, 18% Pb, 12%

Sn) and the commercially available Thermflow™ T443, the embodiment of the present invention demonstrated a thermal resistance of about 0.3 °C/W and the Thermflow™ T443 demonstrated a thermal resistance of about 0.9 °C/W. Thus, the embodiment of the present invention has a considerable thermal conduction advantage over the

5      Thermflow™ T443.

\* \* \* \* \*

Having thus described in detail embodiments of the present invention, it is  
10      understood that the invention defined by the appended claims is not to be limited by  
particular details set forth in the above description, as many apparent variations thereof  
are possible without departing from the spirit or scope thereof.

CLAIMS

What is claimed is:

1. A thermal interface, comprising:  
a grid frame; and  
5 a thermally conductive solder material substantially coating said grid frame.
  
2. The thermal interface of claim 1, wherein said grid frame comprises a thermally conductive material.
  
3. The thermal interface of claim 2, wherein said thermally conductive material selected from the group consisting of aluminum, copper, nickel, and stainless  
10 steel.
  
4. The thermal interface of claim 1, wherein said grid frame comprises a planar, thermally conductive mesh having mesh strands defining substantially square opening.
  
5. The thermal interface of claim 4, wherein said mesh strands comprise  
15 copper material strands on a 50 mil pitch and having a width of about 5 mils and a thickness of about 1.5 mils.

6. The thermal interface of claim 1, wherein said thermally conductive solder material comprises about 49% Bi, about 21% In, about 18% Pb, and about 12% Sn.

7. The thermal interface of claim 1, wherein said thermally conductive solder material comprises about 51% In, about 32.5% Bi, and about 16.5% Sn.

5 8. A device assembly, comprising:  
a heat source;  
a heat dissipation device; and  
a thermal interface, disposed between said heat source and said heat dissipation  
device, comprising a grid frame substantially coated with a thermally conductive solder  
10 material.

9. The device assembly of claim 8, wherein said thermally conductive solder material melts at a temperature at or below a temperature of said heat source.

10. The device assembly of claim 8, wherein said grid frame comprises a  
thermally conductive material.

15 11. The device assembly of claim 10, wherein said thermally conductive  
material selected from the group consisting of aluminum, copper, nickel, and stainless  
steel.

12. The device assembly of claim 8, wherein said grid frame comprises a planar, thermally conductive mesh having mesh strands defining substantially square openings.

13. The device assembly of claim 12, wherein said mesh strands comprise 5 copper material strands on a 50 mil pitch and having a width of about 5 mils and a thickness of about 1.5 mils.

14. The device assembly of claim 8, wherein said thermally conductive solder material comprises about 49% Bi, about 21% In, about 18% Pb, and about 12% Sn.

15. The device assembly of claim 8, wherein said thermally conductive solder 10 material comprises about 51% In, about 32.5% Bi, and about 16.5% Sn.

16. A microelectronic device assembly, comprising:  
a microelectronic die;  
a heat dissipation device; and  
a thermal interface, disposed between said heat source and said heat dissipation 15 device, comprising a grid frame substantially coated with a thermally conductive solder material.

17. The microelectronic device assembly of claim 16, wherein said thermally conductive solder material melts at a temperature at or below an operating temperature of said microelectronic die.

18. The microelectronic device assembly of claim 16, wherein said thermally conductive interface material is substantially solid at room temperature.

19. The microelectronic device assembly of claim 16, wherein said grid frame comprises a thermally conductive material.

5 20. The microelectronic device assembly of claim 16, wherein said thermally conductive material selected from the group consisting of aluminum, copper, nickel, and stainless steel.

10 21. The microelectronic device assembly of claim 16, wherein said grid frame comprises a planar, thermally conductive mesh having mesh strands defining substantially square opening.

22. The microelectronic device assembly of claim 21, wherein said mesh strands comprise copper material strands on a 50 mil pitch and having a width of about 5 mils and a thickness of about 1.5 mils.

15 23. The microelectronic device assembly of claim 16, wherein said thermally conductive solder material comprises about 49% Bi, about 21% In, about 18% Pb, and about 12% Sn.

24. The microelectronic device assembly of claim 16, wherein said thermally conductive solder material comprises about 51% In, about 32.5% Bi, and about 16.5% Sn.
  
25. The microelectronic device assembly of claim 16, further including a support structure which induces a positive pressure between the microelectronic die and  
5 the heat dissipation device.

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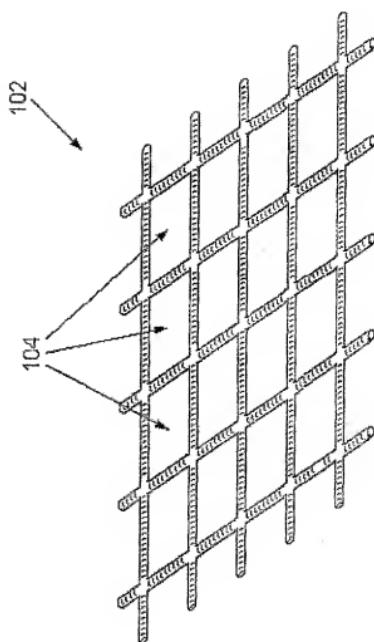


FIG. 1

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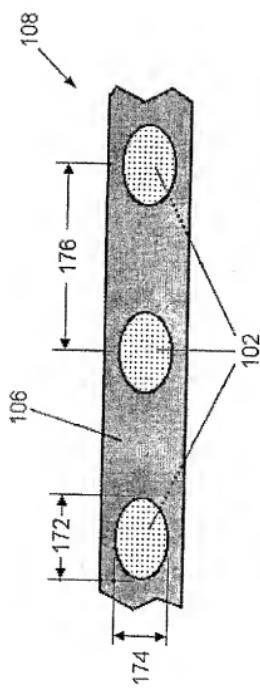
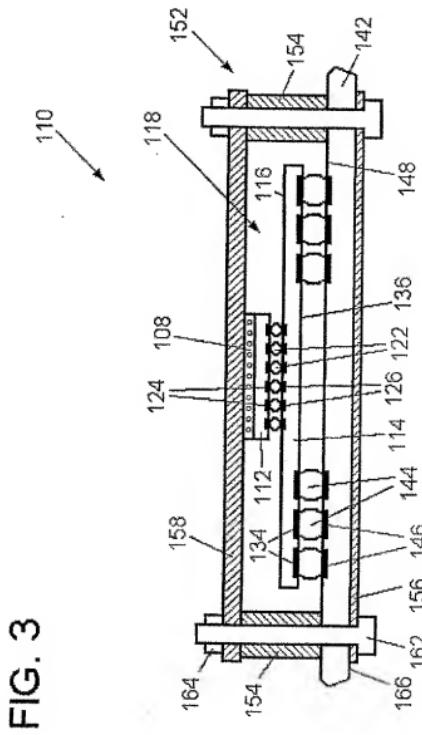
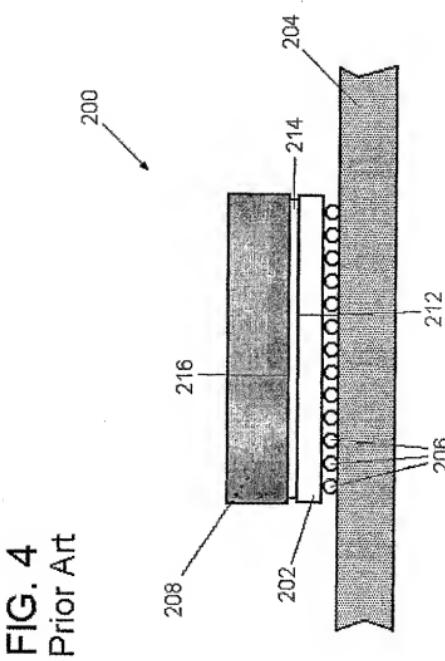


FIG. 2

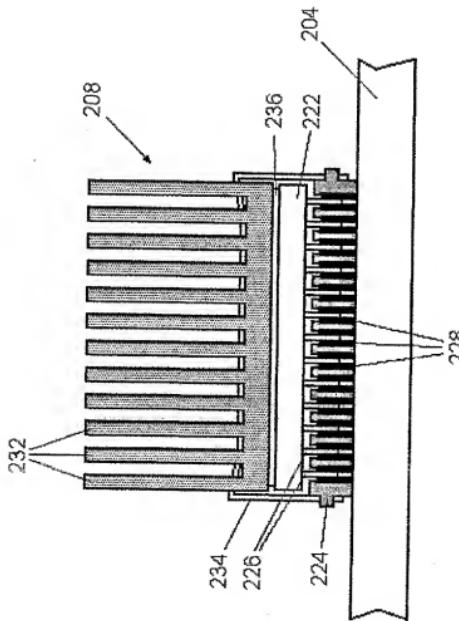
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**FIG. 4**  
Prior Art



**FIG. 5**  
Prior Art

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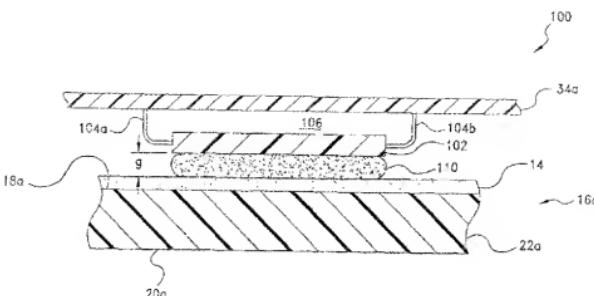
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(54) Title: THERMAL-SPRAYED METALLIC CONFORMAL COATINGS USED AS HEAT SPREADERS



(57) Abstract: Heat dissipation and electromagnetic interference (EMI) shielding for an electronic device having an enclosure. An interior surface of the enclosure is covered with a conformal metallic layer which, as disposed in thermal adjacency with one or more heat-generating electronic components or other sources contained within the enclosure, may provide both thermal dissipation and EMI shielding for the device. The layer may be sprayed onto the interior surface in a molten state and solidified to form a self-adhesive coating.

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ES, FI, FR, GR, GR, HU, IE, IT, LU, MC, NL, PT, RO,  
SL, SI, SK, TR), OAPI patent (BF, BJ, CI, CG, CI, CM,  
GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

*For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.*

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## THERMAL-SPRAYED METALLIC CONFORMAL COATINGS USED AS HEAT SPREADERS

### BACKGROUND OF THE INVENTION

The present invention relates broadly to enclosures, such as cases, cabinets, housings, or parts thereof such as doors or covers, for mobile, i.e., cellular telephone handsets and other electronic devices, and particularly to the manufacture of such 5 enclosures as having a metallic conformal coating which may be used as a heat spreader.

Engineers involved in the design of portable and other electronic systems and devices, such as televisions, radios, computers, mobile, i.e., cellular telephone handsets, medical instruments, business machines, communications equipment, and the like, often 10 face performance problems, as well as government and industrial regulations, concerning electromagnetic interference (EMI). As plastic-housed electronics continue to shrink in size and to run at higher clock speeds, the chances for EMI problems increase. Radio frequency (RF) and digital components, current carrying traces, wires, and other conductors are the typical sources of most EMI emissions. In some cases, the more 15 "noisy" components can be moved away from sensitive areas. However, smaller devices and tightly packed boards minimize that opportunity in a great many systems.

Ultimately, most high-frequency systems require some form of EMI shielding at 20 the enclosure level. These enclosures, which may be a case, cabinet, or housing, or a part thereof such as a door or cover, may be formed of a metal such as steel, aluminum, or magnesium, or alternatively, of a plastic or other polymeric material. While a metal housing is inherently an effective EMI barrier, plastic enclosure parts must be made 25 electrically conductive in order to function as an EMI shield. This has typically been achieved by a conductive layer, such as a paint, metal-filled elastomer, or a metal foil or coating, which may be provided by fastening, laminating, lining, transferring, over-molding, spraying, dipping, cladding, plating, or metallizing, or otherwise which may be applied or deposited across the interior or exterior surfaces of the housing. Although each method may offer certain advantages to the designer, there is almost always a cost-

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performance tradeoff necessary in the selection. Such methods are further described in commonly-assigned of U.S. application Serial No. 10/137,229, in commonly-assigned U.S. Patent No. 5,566,055, in DE 19728839, U.S. Patent Nos. 5,847,317; 5,811,050; 5,442,153; 5,180,639; 5,170,009; 5,150,282; 5,047,260; 4,714,623; and WO 00/29635; 5 99/43191; 99/40769; 98/54942; 98/47340; 97/26782, and in the following publications of the Chomerics Division of Parker Hannifin Corporation (Woburn, MA): "CHO-SHIELD® Conductive Compounds;" "CHO-SHIELD® EMI Shielding Covers," Technical Bulletin 22, (1996); "CHO-VER SHIELD™ EMI Shielding Plastic Cover with Molded Conductive Elastomeric Gasket," (1999); "CHO-SHIELD® 2052 Conductive 10 Coating," Technical Bulletin 48, (2000); "CHO-SHIELD® 2054 Conductive Coating," Preliminary Product Data Sheet, (2000); "CHO-SHIELD® 2056 High Performance Conductive Coating," Preliminary Product Data Sheet; and Ecoplate™ Metallic Conformal Coating Process. The best of these methods will accommodate the deepest recesses in a plastic housing part, where the smallest discontinuity may provide a 15 pathway for spurious emissions.

Managing heat also can be crucial to maintaining the reliability and extending the life of portable and other electronic devices. Numerous cooling solutions, including heat sinks, heat pipes and flexible metal or ceramic heat spreaders, are available for shunting away excess component heat. These solutions typically require a separate heat sink or 20 spreader attached to the heat-generating components. For certain applications, however, a more preferred solution would eliminate the need for such separate heat sinks or spreader.

#### BROAD STATEMENT OF THE INVENTION

25 The present invention is directed to an enclosure, such as a case, housing, or a part thereof such as a housing half or cover, for mobile telephone handsets and other electronic devices. More particularly, the invention relates to a conformal metallic or "metallized" coating layer for such enclosures. In being both electrically-conductive and, it has been discovered, an effective heat conductor, such coating advantageously may be

used to provide both electromagnetic interference (EMI) shielding and thermal management, i.e., heat spreading, for the device. That is, when employed as an EMI shield, such coating also may be used to provide heat spreading for the device and thereby may eliminate the need to provide a separate heat sink or spreader in addition to 5 the EMI shield.

The coating may be applied by means of a thermal spray process to a surface of the enclosure or enclosure part. In an illustrative embodiment, the coating layer is formed by the electric arc spraying of a metal such as tin, copper, zinc, nickel, or an alloy thereof, onto the interior or other surface of a enclosure part which may be diecast, 10 stamped, machined, or, typically, molded of a plastic material such as a polycarbonate (PC), acrylonitrile-butadiene-styrene (ABS), PC/ABS blend, polysulfone, acrylic, polyvinyl chloride (PVC), polyphenylene ether (PPE), polystyrene (PS), polyamide, nylon, polyolefin, or a copolymer or blend thereof. The coating layer so formed is self-adherent and conforms to ribs, wall, and other structures, irregularities, or discontinuities 15 which may be formed enclosure part surface. An electrically-conductive gasket may be dispensed or molded onto the part as chemically-bonded or otherwise self-adhered to the coating layer. Alternatively, the gasket may be adhesively bonded onto the coating layer or mechanically fastened to the part over the coating layer.

As provided on the interior or other surface of the enclosure part, the coating 20 layer may be disposed in thermal adjacency with the integrated circuit (IC) chips and other heat-generating electronic components on the printed circuit board (PCB) or boards of the device for the dissipation of the heat generated by these components. In this regard, a sheet, pad, or other layer of a thermally-conductive interface material may be used to fill the gaps between the coating layer and one or more of the components to provide a 25 low thermal impedance path for the more efficient transfer of heat from the components to the coating layer, which heat then may be dissipated across the surface area of the coating layer and enclosure part for the cooling of the device. Experiments have shown that such a metallic conformal coating layer, which may have a thickness of between about 0.5-100 mils (0.0125-2.5 mm), may be used to provide an EMI shielding

effectiveness, i.e., attenuation, of 60 dB or more while lowering the temperature of the device by 30°C or more.

The present invention, accordingly, comprises the articles and methods of manufacture possessing the construction, combination of elements, and arrangement of parts and steps which are exemplified in the detailed disclosure to follow. Advantages of the present invention include a conformal metallized coating layer which is both an effective heat conductor and EMI shield, and which may be formed reliably and economically on the surface of plastic housing or other enclosure of an electronic device by an electric arc thermal spray process. The coating film so formed is strongly adherent, 10 has a low porosity and oxidation, and requires no curing or further processing. These and other advantages will be readily apparent to those skilled in the art based upon the disclosure contained herein.

#### BRIEF DESCRIPTION OF THE DRAWINGS

15 For a fuller understanding of the nature and objects of the invention, reference should be had to the following detailed description taken in connection with the accompanying drawings wherein:

Fig. 1 is an exploded perspective end view of a handheld electronic communication device representative of a typical application for the enclosure herein involved;

20 Fig. 2 is a perspective view of a back cover of the enclosure of Fig. 1 showing the interior surface thereof as having a thermal spray-applied conformal metallized coating layer in accordance with the present invention;

Fig. 3 is a cross-sectional view of the enclosure part of Fig. 2 taken through line 25 3-3 of Fig. 2;

Fig. 4 is a schematic plan view of a representative electric arc thermal spray system for forming the metallized conformal coating layer of Figs. 2 and 3; and

Fig. 5 is an enlarged cross-sectional, fragmentary assembly view showing a representative EMI shielding and thermal management assembly in accordance with the

present invention wherein a cover or other enclosure part as in Figs. 2-3 is disposed in heat transfer adjacency with a heat-generating electronic component with the gap therebetween being filled with a thermal interface material.

The drawings will be described further in connection with the following Detailed

5 Description of the Invention.

#### **DETAILED DESCRIPTION OF THE INVENTION**

Certain terminology may be employed in the following description for convenience rather than for any limiting purpose. For example, the terms "forward" and 10 "rearward," "front" and "rear," "right" and "left," "upper" and "lower," "top" and "bottom," and "right" and "left" designate directions in the drawings to which reference is made, with the terms "inward," "inner," "interior," or "inboard" and "outward," "outer," "exterior," or "outboard" referring, respectively, to directions toward and away from the center of the referenced element, the terms "radial" or "vertical" and "axial" or 15 "horizontal" referring, respectively, to directions or planes perpendicular and parallel to the longitudinal central axis of the referenced element, and the terms "downstream" and "upstream" referring, respectively, to directions in and opposite that of fluid flow. Terminology of similar import other than the words specifically mentioned above likewise is to be considered as being used for purposes of convenience rather than in any 20 limiting sense. Also as used herein, "state change" may be used interchangeably with "phase change" to avoid confusion with the description of separate material phases, such as a continuous and a dispersed phase, within a compound or layer thereof.

In the figures, elements having an alphanumeric designation may be referenced herein collectively or in the alternative, as will be apparent from context, by the numeric 25 portion of the designation only. Further, the constituent parts of various elements in the figures may be designated with separate reference numerals which shall be understood to refer to that constituent part of the element and not the element as a whole. General references, along with references to spaces, surfaces, dimensions, and extents, may be designated with arrows.

For the illustrative purposes of the discourse to follow, the preparation of the conformal metallic coating of the invention herein involved is described in connection with electric arc thermal spray process. It should be appreciated, however, that other spray processes, such as flame spraying, utilizing alternative ignition sources, such as 5 oxygen, propane, acetylene, natural gas, or other combustible gases, may also be employed. The use of these such other processes, as may be further described in WO 00/29635, therefore should be considered to be expressly within the scope of the present invention.

Referring then to the figures wherein corresponding reference characters are used 10 to designate corresponding elements throughout the several views with equivalent elements being referenced with prime or sequential alphanumeric designations, an exemplary electronic device is shown generally at 10 in the exploded perspective view of Fig. 1 as including a case, housing, or enclosure, reference generally at 12, which is adapted in accordance with the precepts of the present invention as having a metallized 15 conformal coating layer, 14. For purposes of illustration, device 10 is shown to be a mobile telephone handset, but alternatively may be another handheld, portable, or other electronic device such as a personal communications services (PCS) handset, PCMCIA card, modem, wireless communication base station, telemetry or telematic device, global positioning system (GPS), radio receiver, personal digital assistant (PDA), notebook or 20 desktop personal computer (PC), cordless telephone handset, network router or server, medical electronic device, or the like. Enclosure 12 is shown to be of a 2-part construction including a back cover, 16a, and a front cover, 16b, each of the parts 16a-b having a corresponding interior surface, 18a-b, and an exterior surface, 20a-b, which extend coterminously to form adjoining back and front walls, 22a-b, side walls, 24a-b and 25 26a-b, and end walls, 28a-b and 30a-b. Typically, the interiors of one or both of the enclosure parts 16 are divided or partitioned, such as by the wall referenced at 32 for part 16a, into one or more separate cavities for providing electromagnetically isolated compartments for the circuitry of the device 10. As is shown, enclosure 12 may house

one or more printed circuit boards (PCBs), 34a-b, or other circuitry or parts, such as a keypad, 36, of the device 10.

The interior surfaces 18 of the parts 16a-b also extend to define interface surfaces, 40a-b, about the perimeter of each of the enclosure parts 16, and also, as is referenced at 5 42 for wall 32, on the internal walls or other partition structures formed within the parts 16. The interface surfaces 40 and 42 are configured for abutting or other direct or indirect contact engagement with a mating interface surface of the other enclosure part 16, or with a corresponding interface or ground trace surface of a PCB 34 or other part of the device 10. A compressible gasket or other seal, a length of which is shown at 50 as 10 bonded or otherwise supported on interface surface 42, may be interposed between the mating interface or ground trace surfaces. Depending upon the requirements of the application, gasket 50 may extend continuously or discontinuously over all or a portion of the interface surfaces 40 and 42 on one or both of the parts 16a-b. Typically, gasket 50 will be formed of an electrically-conductive material or composite material structure to 15 provide electrical continuity and, optionally, environmental sealing between the mating parts.

Enclosure parts 16a-b, which may be formed of the same or different materials, may be diecast, stamped, or machined of a metal material such as aluminum, zinc, magnesium, steel, or a mixture or alloy thereof. Alternatively, for may handheld or 20 portable applications, parts 16 may be injection molded, thermoformed, or otherwise formed of a plastic, which may be thermoplastic or thermoset, or other polymeric material such as a polycarbonate, acrylonitrile-butadiene-styrene, polysulfone, acrylic, polyvinyl chloride, polyphenylene ether, polystyrene, polyamide, nylon, polyolefin, poly(ether ether ketone), polyimide, polyetherimide, polybutylene terephthalate, 25 polyethylene terephthalate, fluoropolymer, polyester, acetal, liquid crystal polymer, polymethylacrylate, polyurethane, polyphenylene oxide, polystyrene, epoxy, phenolic, or a copolymer or blend thereof.

As formed of a plastic material, the enclosure parts 16 will generally be non-electrically conductive, and coating layer 14 thus may be provided as an electrically-

conductive and, preferably, corrosion-resistant surface on or both of the parts 16. As may be seen with additional reference to Fig. 2 wherein enclosure part 16a is shown in enhanced detail and to the magnified cross-sectional view thereof of Fig. 3, layer 14 may be characterized as an adherent, electrically-conductive film or other coating or the like

5 which is applied to cover at least a portion of one or both of the interior surfaces 18a-b of the corresponding enclosure part 16a-b. For many applications, shielding layer 14 will have a film thickness, referenced at "t" in Fig. 3, of between about 0.5-100 mils (0.0125-2.5 mm), with the enclosure parts 16a-b having a thickness, referenced at "T" in Fig. 3 of between about 0.020-0.250 inch (0.05-1 cm).

10 In an illustrative embodiment, the metallized coating layer 14 is thermally-sprayed, such as by means of standard arc wire equipment, onto at least a portion of and, typically, substantially the entirety of the interior surfaces 18 and interface surfaces 40 and 42 of each of the parts 16a-b. For corrosion resistance, layer 14 may be formed of tin, nickel, or an alloy thereof. Alternatively, layer 14 may be formed of copper, silver, zinc, or other metal or alloy. Typically, the composition of layer 14 may comprise between about 80-95% by weight of tin or nickel, and between about 5-20% by weight of one or more of zinc, copper, or aluminum. Trace amounts of other metals, elements, and organic or inorganic compounds also may be present. Such material is economical and provides a corrosion-resistant coating on surface 18. In this regard, layer 14 typically

15 will exhibit a less than about 5-15% increase in surface resistance upon exposure to a salt-fog environment for about 48 hours at about 35°C. Layer 14 similarly will be observed to exhibit substantially no increase in surface resistance following a thermal cycling of at least about 5 cycles at -40°C to 85°C with a dwell time of about two hours at each of the upper and lower temperature limits.

20

25 Advantageously, as thermally-sprayed in accordance with the present invention, coating layer 14 is self-adherent to interior surface 18 as being bonded thereto. Such bond principally will be by way of mechanical forces, but additionally may include fusion or chemical bonding, and/or electrostatic, van der Waals, or other valance or attractive forces depending upon the composition and the compatibility of the metal or

plastic material forming surface 18 and the metal material forming the metallized coating layer 14. Typically, layer 14 will be observed to have an assigned rating of about "5B," i.e., substantially no coating pickoff, as determined on a scale of 0B-5B in accordance with ASTM Test Method D3359-97, "Standard Test Methods for Measuring 5 Adhesion by Tape Test," in which the adhesion of coatings is assessed by applying and removing pressure-sensitive tape over cross-hatch cuts made in the coating.

Prior to the metallizing of layer 14 thereon, surface 18 may be cleaned, etched, roughened, or otherwise treated or modified such as by means of one or more of compressed gas, chemical or solvent etching/cleaning, grit-blasting, such as with 10 aluminum oxide or another abrasive, or other known surface treatment such as corona discharge or plasma ionization. Alternatively, a chemical bond coat, such as a thermoplastic dissolved in a solvent, may be applied to the surface 18 and dried or otherwise cured thereon to form an intermediate tie layer between the surface and the metallized layer 14.

15 As an addition or an alternative to the above-described surface treatments, the metallizing may be effected at an elevated substrate temperature, such as 50°C or higher, so as to increase the surface energy of the surface 18. However, the metallizing also may be performed at ambient temperature so as to avoid any potential for heat distortion and other dimensional, physical, or chemical changes in the substrate material. Depending 20 upon the requirements of the particular application involved, areas of surface 18 may be masked, such as by means of a overlay cut-out, to prevent the deposition of shielding layer 14 on those areas. As mentioned, and as may be seen best in the cross-sectional view of Fig. 3, the coating layer 14 formed in accordance with the present invention is conformal in that it is able to cover ribs, stiffeners, bosses, deep draws, vertices, and other 25 surface asperities, irregularities, or discontinuities, such as the generally vertical surfaces 60a-b of wall 32.

With continuing reference to Fig. 3, gasket 50 may be seen to be disposed following the metallization of surface 18 on the portion 62 of layer 14 covering the interface surface 42. Such gasket 50 may be provided as having a resilient core element

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affording gap-filling capabilities which is either loaded, sheathed, or coated with an electrically conductive element. The resilient core element, which may be foamed or unfoamed, solid or tubular, typically is molded, extruded, die-cut, or otherwise formed of an elastomeric thermoplastic material such as a polyolefin, polyvinyl chloride, or a

5 polypropylene-EPDM blend, or a thermoplastic or thermosetting rubber such as a butadiene, styrene-butadiene, nitrile, chlorosulfonate, neoprene, urethane, silicone, or fluorosilicone.

Conductive materials for the filler, sheathing, or coating include metal or metal-plated particles, fabrics, meshes, and fibers. Preferred metals include copper, nickel, silver, aluminum, tin or an alloy such as Monel, with preferred fibers and fabrics including natural or synthetic fibers such as cotton, wool, silk, cellulose, polyester, polyamide, nylon, polyimide. Other conductive particles and fibers such as carbon, graphite, plated glass, or a conductive polymer material may be substituted. The gasket, alternatively, may be provided to be of an all-metal, knitted wire construction, or as a

10 over-molded or formed-in-place (FIP) bead of a curable, electrically-conductive silicone or urethane composition. As to an FIP construction, the composition is dispensed in a fluent state onto the surface 42 and the layer 14 portion 62 thereon, then is cured or foamed in situ via the application of heat or with atmospheric moisture, UV, radiation, or other energy sources.

15 Means of securing gasket 50 to the layer portion 62 include pressure-sensitive adhesive tapes or other layers (not shown), which may be filled to be electrically conductive, interposed between the layer 14 portion 62 and the gasket. Alternatively, mechanical means of attachment such as clips, fasteners, or a tongue-in-groove or other interference fit may be employed. In the case of an over-molded or FIP construction, the

20 gasket 50 may be self-bonded by chemical, mechanical, or other adhesive forces to the layer 14 portion 62. EMI shielding gaskets and their methods of manufacture and use are further described in U.S. Patent Nos. 6,121,545; 6,096,413; 5,910,524; 5,882,729; 5,731,541; 5,641,438; 5,603,514; 5,578,790; 5,566,055; 5,524,908; 5,522,602; 5,512,709; 5,438,423; 5,202,536; 5,142,101; 5,115,104; 5,107,070; 5,105,056; 5,068,493; 5,028,739;

5,008,485; 4,988,550; 4,968,854; 4,952,448; 4,857,668; and 3,758,123, and in WO 96/22672 and 98/54942; Japanese Patent Publication (Kokai) No. 7177/1993; DE 19728839, and Severinsen, J., "Gaskets That Block EMI," Machine Design, Vol. 47, No. 19, pp. 74-77 (August 7, 1975).

5       Turning next to Fig. 4, a schematic diagram of a representative arc wire system adapted for the thermal spraying of shielding layer 14 onto interior surface 18a of enclosure part 16a is referenced generally at 70. In the system 70, a pair of electrically-conductive, consumable wire electrodes, 72a-b, are feed via a corresponding roller arrangement, 74a-b, or other mechanism through a pair of contact tubes, 76a-b, which

10      15 may be housed within a nozzle, referenced generally at 78, of a gun or other spray head. Each of the wire electrodes 72, which may be of the same or difference composition, may be provided in accordance with the present invention as formed of the tin, nickel, or alloy metal further described hereinbefore. The wire sizes and feed rates may be varied depending on the application, but generally would be considered conventional for the arc

15      15 wire process herein involved.

With one of the contact tubes 76a-b being held, for example, at a positive voltage potential, such as is referenced at  $V_+$ , and with the other of tubes 76a-b being held at a negative voltage potential, such as is referenced at  $V_-$ , a corresponding electrical potential difference may be induced in the wire electrodes 72 by virtue of their conductive contact

20      25 with an associated on of the tubes 76. Such potential difference is manifested as an electric arc which is generated within a gap or "arc zone," located generally in the area referenced at 80, maintained between the tips of the wires 72. As the wires 72 are feed continuously into the arc zone, heat generated resistively by the arc raises the temperature of the wires to above their corresponding liquidus temperature, typically between about 200-500°C, and thereby causes the tips of the wires to melt. The melt produced is atomized into a spray, 82, of droplets by a primary gas stream, the direction of which is denoted by the arrow 84, which stream 84 may be compressed air supplied into the arc zone 80 through a centrally-located tube or other passageway, 86. Additional atomization or containment of the spray 82 may be effected by a secondary gas stream,

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the direction of which is denoted by the 88, which stream 88 may be introduced within a shield, 90, which surrounds the orifice or outlet, 92, of the nozzle 78.

The force of the atomizing gas streams 84 and 88 also accelerates the droplets of the spray 82 towards the workpiece, represented in Fig. 4 by the housing part 16a of Figs. 5 1-3, which may be positioned a spaced-apart distance, typically between about 4-24 inches (10-60 cm), opposite the nozzle 78 as received on a table, conveyor, or other support, 94. As is known, one or both of the nozzle 78 or workpiece 16a may be moved relative to other to provide complete coverage of the substrate surface 18 by the spray 82. For example, the nozzle 78 may be mounted for movement along one or more axes on a 10 gantry or an articulated robotic arm. The molten droplets of spray 82 solidify and fuse rapidly upon impact with the surface 18 to form an adherent coating of the shielding layer 14 of the invention theron. Depending upon the thickness of the layer 14 required, single or multiple passes of the spray 82 over the surface 18 may be performed.

Referring lastly to Fig. 5, a representative EMI shielding and thermal 15 management assembly in accordance with the present invention is referenced generally at 100. In the assembly 100, a housing half, cover, or other enclosure part, such as part 16a as in Figs. 1-4 having the layer 14 formed as described hereinbefore or otherwise as provided, is disposed in the assembled device 10 (see Fig. 1) in confronting or other heat transfer adjacency with one or more of the heat-generating analog, digital, or other 20 electronic components, such as the component referenced at 102, supported on the PCB 34a or other substrate within the device 10.

Component 102 may be an integrated microchip, microprocessor, transistor, or other power semiconductor device, an ohmic or other heat-generating subassembly such as a diode, relay, resistor, transformer, amplifier, diac, or capacitor, or, alternatively, 25 another heat-generating source, and typically, component 58 will have an operating temperature range of between about 60-100°C. For the electrical connection of component 102 to PCB 34a, one or more pairs of solder balls, leads, or pins, one pair of which is referenced at 104a-b, are provided as extending from component 102 into a soldered or other connection with PCB 34a. Leads 104 additionally may support, as is

shown, component 104 above PCB 34a to define a gap, referenced at 106, of about 3 mils (75 microns) therebetween. Alternatively, component 102 may be received directly on PCB 34a.

With the part 16a having the applied layer 14 being disposed as shown in 5 opposition or like thermal adjacency one or more of the components 102, a gap, referenced at "g," is defined therebetween the layer and one or more, or each, of the components 102 which may range, for example, from about 2 mils (0.05 mm), or less, to about 100 mils (2.5 mm), or more. For at least partially filling the gap g to provide a lower thermal impedance path for the more efficient transfer of heat from one or more, or 10 each, of the components 102 to the coating layer 14, which heat then may be dissipated across the surface area of the layer 14 and enclosure part 16a for the cooling of the device 10 (Fig. 1), a sheet, pad, or other layer, 110, of a thermal interface material may be interposed or, such as in the case of a form-in-place compound, dispensed between one or more, or each, of the components 102 and the layer 14.

15 Such material forming layer 110 may be an admixture of a filler and a resin. The filler generally may be thermally-conductive as having a thermal conductivity of at least about 20 W/m-K, and may comprise oxide, nitride, carbide, diboride, graphite, or metal particles, or a mixture thereof. The resin, which may be a homopolymer, copolymer, or blend, may comprise an elastomer such as a silicone or polyurethane, or a phase-change 20 material (PCM). Formulated as described, the admixed material may have a thermal conductivity, such as in accordance with ASTM D5470, of at least about 0.5 W/m-K.

Within the gap g, the material generally may conform, such as under an applied 25 pressure developed by the mating of the housing parts 16a-b, to at least partially fill the gap g. Depending upon the requirements of the particular application, the material 110 may be selected to be conformable or otherwise compliant under a relative low or substantially no force, that is, for example, a compression or force deflection of about 25% at about 0.3 psi (2 kPa), and of about 50% at about 1 psi (6 kPa) or less. Thermal interface materials are further described in U.S. Patent Nos. 6,096,414; 6,054,198; 5,798,171; 5,766,740; 5,679,457; 5,545,473; 5,533,256; 5,510,174; 5,471,027; 5,359,768;

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5,321,582; 5,309,320; 5,298,791; 5,250,209; 5,213,868; 5,194,480; 5,137,959; 5,167,851; 5,151,777; 5,060,114; 4,979,074; 4,974,119; 4,965,699; 4,869,954; 4,842,911; 4,782,893; 4,764,845; 4,685,987; 4,654,754; 4,606,962; 4,602,678; 4,473,113; 4,466,483; 4,299,715; and 3,928,907. Additional thermal interface material also may be used to fill 5 the gap 106.

Particularly as employed within the EMI shielding and thermal management assembly 100, coating layer 14 may be formed so as to exhibit an electrical surface resistance of not greater than about 0.10  $\Omega$ /sq., and to provide an EMI shielding effectiveness, such as in accordance with CHO-TM-TP08 TP57 (Chomerics Test 10 Procedure, Parker Chomerics Division, Woburn, MA), of at least about 60 dB substantially over a frequency range of between about 10 MHz and about 2 GHz. Such layer 14, moreover, may be so formed as to exhibit a thermal conductivity, such as in accordance with ASTM D5470, of at least about 5 W/m-K.

Although, as mentioned, and particularly for corrosion resistance, layer 14 may be 15 formed of tin, nickel, or an alloy thereof, the layer alternatively may be formed of another metal or alloy, such as copper, having a relatively higher thermal conductivity and thereby allowing for a reduction in the film thickness of the coating layer while affording comparable thermal performance.

Although the coating layer 14 is shown in Fig. 5 to be generally homogeneous, a 20 composite, i.e., laminate, arrangement of two or more layers of different materials, one deposited on top of the other, also may be used. For example, a first of such layers, which may be an inner or outer layer, may be more, or less, thermally conductive than a second of such layers which, in turn, may be more or less corrosion-resistant, or more or less adherent to the surface 18a, than the first layer. A specific example would be the 25 deposition of tin-zinc alloy layer on top of an inner copper alloy layer for the purpose of protecting the copper from oxidation.

Furthermore, although the coating layer 14 also is shown in the figures herein to cover the entirety, or substantially the entirety of the surface 18a, it should be appreciated that the layer 14 may be deposited in a specific pattern so as to function as a "heat pipe."

In such an arrangement, the heat transferred from the component 102 may be channelled along a path defined by the coating pattern to a specified point or member, such as a heat sink, for dissipation.

Thus, the use of thermal-sprayed or otherwise deposited metal and metal alloys as 5 conformal coating or other covering layers on the surfaces of enclosures, enclosure parts, and the like have been described. Such layers may be used within assemblies such as electronic devices to provide either or, advantageously, both EMI shielding and thermal management for the device, and without the need to provide a separate heat sink or spreader, i.e., in addition to the EMI shield.

10 The Example to follow, wherein all percentages and proportions are by weight unless otherwise expressly indicated, is illustrative of the practicing of the invention herein involved, but should not be construed in any limiting sense.

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## EXAMPLE

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Representative coating samples according to the present invention were prepared 20 for characterization using an electric-arc thermal spray process. Individual panels of a 0.125 inch (3.175 mm) thick acrylonitrile-butadiene-styrene (ABS) sheet, representative of a plastic housing or case, were coated with a 1.5, 4.0, 11.0 or 17.3 mil (0.04, 0.10, 0.28, or 0.44 mm) thick layer of an 80% Sn, 20% Zn alloy. The coated sheets were cut into 2 x 2 inch (5 x 5 cm) panels for testing.

25 In each test, a Type "T" thermocouple was attached with thermally conductive adhesive tape to the center of the uncoated surface of each of the test panels to measure "skin" temperature. A 0.75 x 0.75 inch (1.9 x 1.9 cm) pad of a 0.07 inch (1.78 mm) thick thermally-conductive thermal interface material was interposed between a heat source and the panel. The pad, which included a layer of aluminum foil on one side, was 30 attached to the center of the test panel with the foil surface adjacent the coating layer side of the panel. The heat source, a TIP31 power semiconductor device in a TO220 package,

was attached through its base to the other (elastomer) surface of the pad. It was noted that the elastomer surface of the pad was sufficiently tacky to maintain thermal contact with the device throughout the test.

The TIP31 device was connected to an Analysis Tech Phase 10 Thermal Analyzer 5 to power the device and perform the temperature measurements. Device junction, ambient and plastic and plastic case temperatures were recorded upon thermal equilibrium being established. Thermal resistance (R) values also were determined. The results are summarized in the table below.

TABLE

Thickness (mils)	Power (watts)	T <sub>junction</sub> (°C)	T <sub>case</sub> (°C)	T <sub>ambient</sub> (°C)	R <sub>junction-case</sub> (°C/W)	R <sub>junction-ambient</sub> (°C/W)
0	2.02	110.8	74.6	22.2	17.8	43.8
1.5	2.02	103.7	67.3	21.2	18.0	40.7
4.0	2.02	94.5	60.2	21.8	17.0	35.9
11.0	2.02	86.8	54.0	20.9	16.2	32.5
17.3	2.02	81.3	48.0	22.1	16.4	29.2

These data show that the metallic conformal coating of the present invention, in layers as thin as 1.5 (0.04) mil or less, is effective to dissipate the heat generated by a semiconductor device, and to reduce the overall heat load that the plastic case must 15 dissipate into the environment. Such thermal dissipation performance reduces the junction temperature of the device as well as the potential for hot spots on the case. Indeed, the result for the 4.0 mil (0.10 mm) thick coating sample is especially significant effect insofar as the junction temperature was reduced by 15°C and the case temperature was reduced to 60°C. Such a reduction in the case temperature is of practical importance 20 as a case temperature over 60°C can cause burns when touched.

As it is anticipated that certain changes may be made in the present invention without departing from the precepts herein involved, it is intended that all matter contained in the foregoing description shall be interpreted in as illustrative rather than in a limiting sense. All references including any and all priority documents cited herein are 25 expressly incorporated by reference.

CLAIMS

What is claimed is:

1. A method of dissipating heat from an electronic device having an enclosure and at least one heat-generating source received within the enclosure, the enclosure having one or more parts, and at least one of the parts having an exterior surface and an opposing interior surface, the method comprising the steps of:
  - 5 (a) covering at least a portion of the interior surface of said one of the enclosure parts with a conformal metallic layer; and
  - (b) disposing the conformal metallic layer covered on said one of the enclosure parts and the source in heat transfer adjacency with each other.
2. The method of claim 2 wherein the metallic layer comprises tin, nickel, copper, zinc, aluminum, silver, or an alloy thereof.
3. The method of claim 1 wherein the interior surface of said one of the enclosure parts is covered in step (a) by the steps of:
  - (i) providing a feed material comprising a metal or metal alloy;
  - (ii) heating said feed material of step (i) into a molten state;
  - 5 (iii) atomizing said feed material of step (ii) while in said molten state;
  - (iv) spraying the atomized feed material of step (ii) while in said molten state on said portion of the interior surface of said one of the enclosure part to form a self-adherent coating of said metal thereon; and
  - (v) solidifying said coating of step (iii) to form said conformal metallic layer.
4. The method of claim 1 wherein the conformal metallic layer covering said one of the enclosure parts and the source are disposed in step (b) to define a gap therebetween, said method further comprising the additional step before or after step (b) of interposing a thermal interface material between the conformal metallic layer covered

5 on said one the enclosure parts and the source, said thermal interface material at least partially filling said gap.

5. The method of claim 4 wherein the thermal interface material comprises an admixture of a resin and a filler.

6. The method of claim 1 where the heat-generating source is an electronic component.

7. The method of claim 6 where the electronic component is mounted on a circuit board.

8. The method of claim 1 wherein said housing part is formed of a plastic.

9. The method of claim 8 wherein said plastic is polycarbonate, acrylonitrile-butadiene-styrene, polysulfone, acrylic, polyvinyl chloride, polyphenylene ether, polystyrene, polyamide, nylon, polyolefin, poly(ether ether ketone), polyimide, polyetherimide, polybutylene terephthalate, polyethylene terephthalate, fluoropolymer, 5 polyester, acetal, liquid crystal polymer, polymethylacrylate, polyurethane, polyphenylene oxide, polystyrene, epoxy, phenolic, or a copolymer or blend thereof.

10. The method of claim 1 wherein the metallic layer has a thermal conductivity of at least about 5 W/m-K.

11. The method of claim 1 wherein the metallic layer exhibits an EMI shielding effectiveness of at least about 60 dB substantially over a frequency range of between about 10 MHz and about 2 GHz.

12. The method of claim 1 wherein the metallic layer has an electrical surface resistance of not greater than about 0.10  $\Omega$ /sq.

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13. The method of claim 1 wherein said shielding layer of step (e) has a thickness of between about 0.5-100 mils (0.0125-2.5 mm).

14. The method of claim 3 wherein said feed material is heated in step (a)(ii) by generating an electric arc within an arc zone, and passing said feed material through said arc zone.

15. The method of claim 14 wherein:

said feed material is atomized in step (a)(iii) by a gas stream passed with said feed material through said arc zone; and

said feed material is sprayed in step (a)(iv) by entrainment within said gas stream.

16. The method of claim 14 wherein:

said feed material is provided as a first wire and a second wire, each said wire being passed with the other said wire through said arc zone; and

wherein said arc is generated by applying an electrical potential difference  
5 between said first and said second wire.

17. A thermal management assembly for an electronic device having an enclosure and at least one heat-generating source received within the enclosure, the enclosure having one or more parts, and at least one of the parts having an exterior surface and an opposing interior surface, the assembly comprising a conformal metallic  
5 layer covering at least a portion of the interior surface of said one of the enclosure parts, and being disposed in heat transfer adjacency with the source received within the enclosure.

18. The assembly of claim 17 wherein the metallic layer comprises a self-adherent coating of a metal or metal alloy.

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19. The assembly of claim 18 wherein the metallic layer comprises tin, nickel, copper, zinc, aluminum, silver, or an alloy thereof.

20. The assembly of claim 17 wherein the conformal metallic layer covering said one of the enclosure parts is disposed in said heat transfer adjacency with the source received within the enclosure to define a gap therebetween, said assembly further comprising a thermal interface material interposed between the conformal metallic layer 5 and the source, said thermal interface material at least partially filling said gap.

21. The assembly of claim 20 which consists for the source essentially of the conformal metallic layer and the thermal interface material.

22. The assembly of claim 20 wherein the thermal interface material comprises an admixture of a resin and a filler.

23. The assembly of claim 17 where the heat-generating source is an electronic component.

24. The assembly of claim 23 where the electronic component is mounted on a circuit board.

25. The assembly of claim 17 wherein said housing part is formed of a plastic.

26. The assembly of claim 25 wherein said plastic is polycarbonate, acrylonitrile-butadiene-styrene, polysulfone, acrylic, polyvinyl chloride, polyphenylene ether, polystyrene, polyamide, nylon, polyolefin, poly(ether ether ketone), polyimide, polyetherimide, polybutylene terephthalate, polyethylene terephthalate, fluoropolymer, 5 polyester, acetal, liquid crystal polymer, polymethylacrylate, polyurethane, polyphenylene oxide, polystyrene, epoxy, phenolic, or a copolymer or blend thereof.

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27. The assembly of claim 17 wherein the metallic layer has a thermal conductivity of at least about 5 W/m-K.

28. The assembly of claim 17 wherein the metallic layer exhibits an EMI shielding effectiveness of at least about 60 dB substantially over a frequency range of between about 10 MHz and about 2 GHz.

29. The assembly of claim 17 wherein the metallic layer has an electrical surface resistance of not greater than about 0.10  $\Omega$ /sq.

30. The assembly of claim 17 wherein said shielding layer of step (e) has a thickness of between about 0.5-100 mils (0.0125-2.5 mm).

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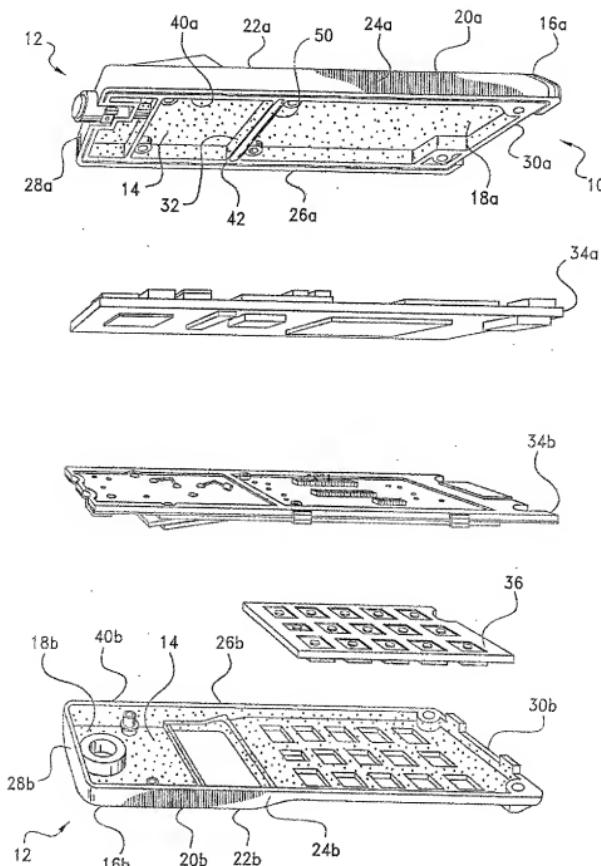


Fig. 1

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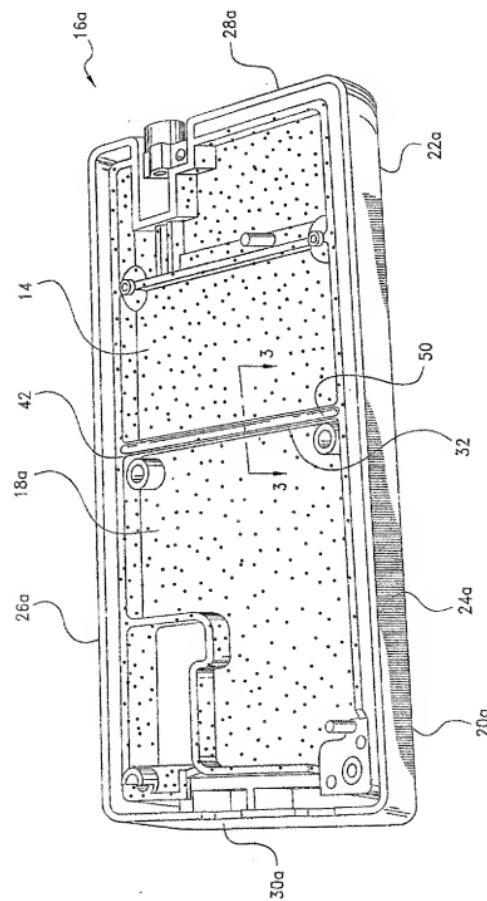


Fig. 2

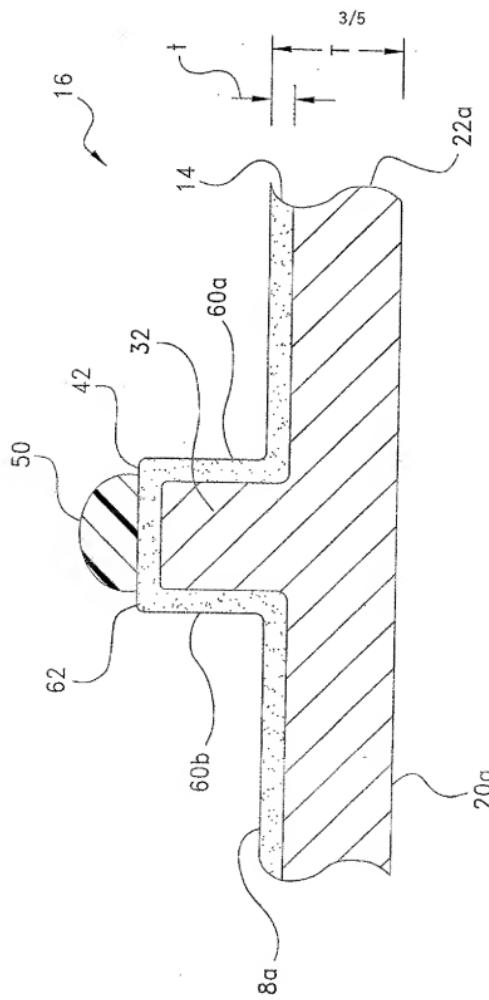


Fig. 3

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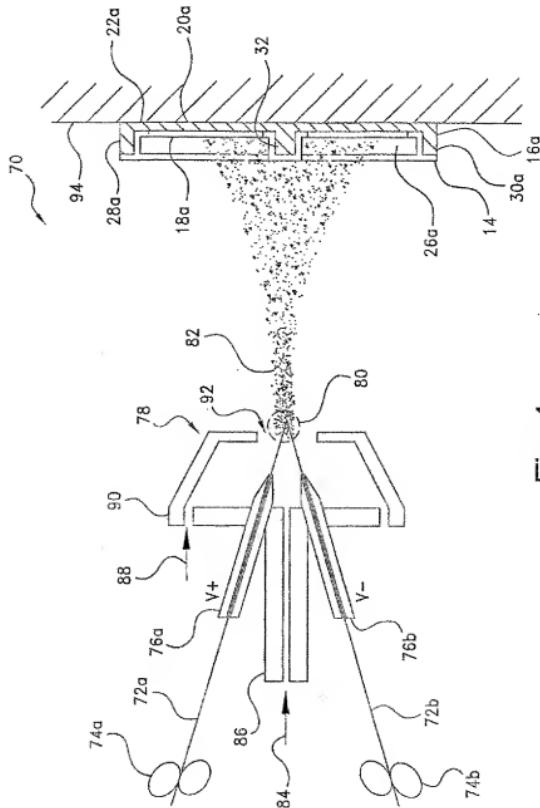


Fig. 4

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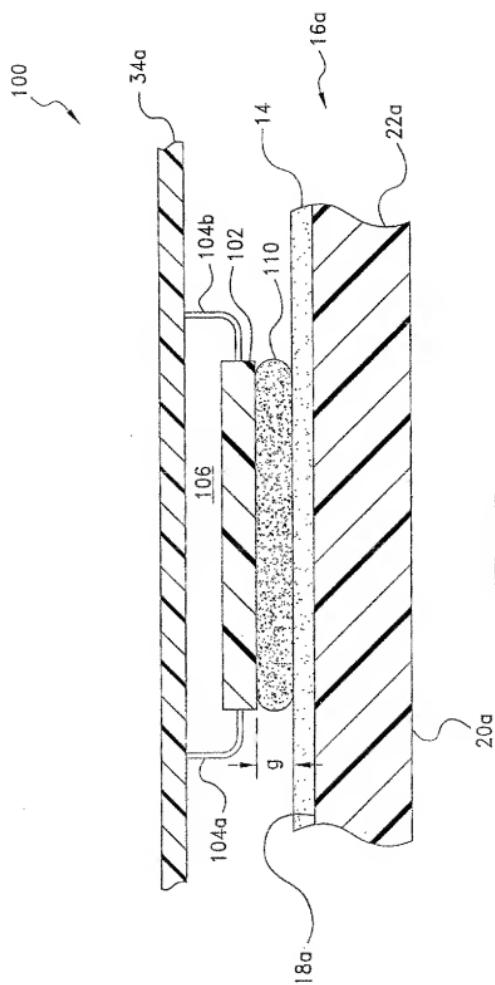


Fig. 5

## INTERNATIONAL SEARCH REPORT

Internal Application No  
PCT/US 03/28858A. CLASSIFICATION OF SUBJECT MATTER  
IPC 7 H05K7/20 C23C4/12

According to International Patent Classification (IPC) or to both national classification and IPC

## B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)  
IPC 7 H05K C23C

Documentation searched other than minimum documentation (to the extent that such documents are included in the fields searched)

Electronic data base consulted during the International search (name of data base and, where practical, search terms used)

EPO-Internal, WPI Data, PAJ

## C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	US 6 049 469 A (BRODER DAMON W ET AL) 11 April 2000 (2000-04-11)	1,6-9, 13,17, 22-26,30
Y	column 8, line 8-67; figure 3	2-5, 14-16, 18-22
Y	GB 2 320 929 A (GEN ELECTRIC) 8 July 1998 (1998-07-08)	2,3, 14-16, 19,21
Y	page 2, line 27 -page 3, line 12	—
Y	US 6 195 267 B1 (MACDONALD JR JAMES D ET AL) 27 February 2001 (2001-02-27) column 3, line 26 -column 4, line 41; figures 1-3	4,5, 20-22
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 Further documents are listed in the continuation of box C. Patent family members are listed in annex.

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13 January 2004

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## INTERNATIONAL SEARCH REPORT

Internal ref.	Application No.
PCT/US 03/28858	

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Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
Y	WO 00 29635 A (THERMOCERAMIX L L C ;COLLIER PAUL S (US); GLENN WILLIAM A (US); AB) 25 May 2000 (2000-05-25) page 17, line 20,21 _____	18

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